

October 13, 2026

Nidec Advance Technology to Exhibit Products at TPCA Show TAIPEI 2026

Nidec Advance Technology Corporation (“Nidec Advance Technology” or the “Company”) announced today that it will exhibit products at TPCA Show TAIPEI 2026, an international exhibition scheduled to take place at Taipei South Port Exhibition Center from Tuesday, October 20 – Thursday, October 22, 2026.



TPCA Show TAIPEI 2026, to be hosted by Taiwan Printed Circuit Association (TPCA), will showcase all products and technologies related to the printed circuit board (PCB) industry, including: electronic circuits and mounting technology for electronics, information and communications, control equipment, etc.; and raw materials and chemical goods that compose electronic substrates.

At this upcoming event, based on the theme, **“Revolutionary inspection technology to support quality in the age of AI,”** Nidec Advance Technology will present solutions optimized to meet the needs of the electronics industry, which constantly evolves to secure the quality of high-end circuit substrates that are becoming increasingly fine, and large and dense due to heterogeneous integration.

Furthermore, the Company will exhibit its X-ray inspection solution for back-drilling, and EFEM (Equipment Front End Module), an automatic transport machine born out of the Nidec Group’s internal synergies. In addition, as existing image and electrical inspection equipment become increasingly precise as well, Nidec Advance Technology will propose total inspection solutions that meet the quality levels required for cutting-edge products.

About TPCA Show TAIPEI 2026

- Period: Tuesday, October 20 – Thursday, October 22, 2026
- Venue: Taipei South Port Exhibition Center (TaiNEX 1)
- Booth: K-725
- Official website: <https://www.tpcashow.com/en/>

Nidec Advance Technology’s main exhibits will include:

- GATS®-7885 (conduction/short-circuit inspection equipment for FOPLP/RDL)
- GATS®-8370 (full-panel substrate inspection equipment multi-face semiconductor package arrangement)
- GATS®-7837 (high-accuracy inspection equipment for large-piece semiconductor packages)
- STAR REC®V6 (conduction insulation inspection equipment for large-size/multiple-pin substrates)
- GATS®-8360 (CoWoP-responsive conduction/short-circuit inspection equipment for large HDI)
- RSH Series (2D/3D optical inspection equipment responsive to high-density substrates)

- AURCA Series (next-generation AI visual inspection equipment responsive to optical modules and large-size substrates)
- High-accuracy inspection solution for TGV (Through Glass Via)
- NS probe (jig solution responsive to narrow pitches)

Machines to be exhibited:

- High-speed, CT-type X-ray machine for back-drilling
- AVR SMV 3000 (automatic wafer transport machine EFEM) (developed jointly with Nidec Instruments Corporation)

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